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## Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

## **Applications of Embedded - FPGAs**

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

### **Details**

Product Status	Obsolete
Number of LABs/CLBs	150
Number of Logic Elements/Cells	1200
Total RAM Bits	9421
Number of I/O	113
Number of Gates	-
Voltage - Supply	1.71V ~ 3.465V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	144-LQFP
Supplier Device Package	144-TQFP (20x20)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo1200c-3t144c">https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo1200c-3t144c</a>

June 2013

Data Sheet DS1002

### Features

- **Non-volatile, Infinitely Reconfigurable**
  - Instant-on – powers up in microseconds
  - Single chip, no external configuration memory required
  - Excellent design security, no bit stream to intercept
  - Reconfigure SRAM based logic in milliseconds
  - SRAM and non-volatile memory programmable through JTAG port
  - Supports background programming of non-volatile memory
- **Sleep Mode**
  - Allows up to 100x static current reduction
- **TransFR™ Reconfiguration (TFR)**
  - In-field logic update while system operates
- **High I/O to Logic Density**
  - 256 to 2280 LUT4s
  - 73 to 271 I/Os with extensive package options
  - Density migration supported
  - Lead free/RoHS compliant packaging
- **Embedded and Distributed Memory**
  - Up to 27.6 Kbits sysMEM™ Embedded Block RAM
  - Up to 7.7 Kbits distributed RAM
  - Dedicated FIFO control logic

**Table 1-1. MachXO Family Selection Guide**

Device	LCMXO256	LCMXO640	LCMXO1200	LCMXO2280
LUTs	256	640	1200	2280
Dist. RAM (Kbits)	2.0	6.1	6.4	7.7
EBR SRAM (Kbits)	0	0	9.2	27.6
Number of EBR SRAM Blocks (9 Kbits)	0	0	1	3
V <sub>CC</sub> Voltage	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V
Number of PLLs	0	0	1	2
Max. I/O	78	159	211	271
<b>Packages</b>				
100-pin TQFP (14x14 mm)	78	74	73	73
144-pin TQFP (20x20 mm)		113	113	113
100-ball csBGA (8x8 mm)	78	74		
132-ball csBGA (8x8 mm)		101	101	101
256-ball caBGA (14x14 mm)		159	211	211
256-ball ftBGA (17x17 mm)		159	211	211
324-ball ftBGA (19x19 mm)				271

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### Architecture Overview

The MachXO family architecture contains an array of logic blocks surrounded by Programmable I/O (PIO). Some devices in this family have sysCLOCK PLLs and blocks of sysMEM™ Embedded Block RAM (EBRs). Figures 2-1, 2-2, and 2-3 show the block diagrams of the various family members.

The logic blocks are arranged in a two-dimensional grid with rows and columns. The EBR blocks are arranged in a column to the left of the logic array. The PIO cells are located at the periphery of the device, arranged into Banks. The PIOs utilize a flexible I/O buffer referred to as a sysIO interface that supports operation with a variety of interface standards. The blocks are connected with many vertical and horizontal routing channel resources. The place and route software tool automatically allocates these routing resources.

There are two kinds of logic blocks, the Programmable Functional Unit (PFU) and the Programmable Functional unit without RAM (PFF). The PFU contains the building blocks for logic, arithmetic, RAM, ROM, and register functions. The PFF block contains building blocks for logic, arithmetic, ROM, and register functions. Both the PFU and PFF blocks are optimized for flexibility, allowing complex designs to be implemented quickly and effectively. Logic blocks are arranged in a two-dimensional array. Only one type of block is used per row.

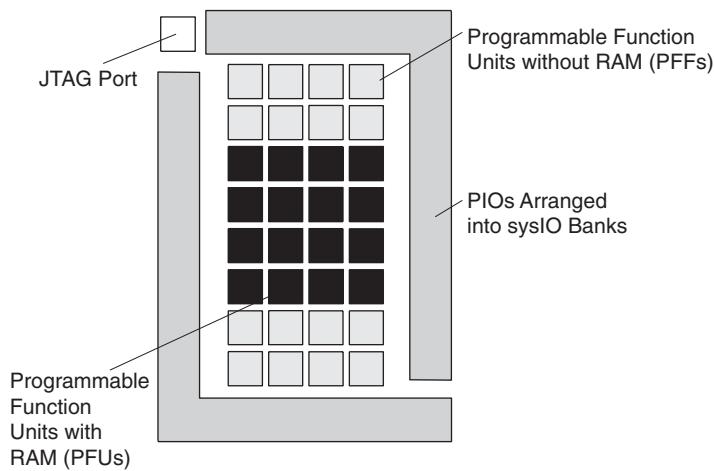
In the MachXO family, the number of sysIO Banks varies by device. There are different types of I/O Buffers on different Banks. See the details in later sections of this document. The sysMEM EBRs are large, dedicated fast memory blocks; these blocks are found only in the larger devices. These blocks can be configured as RAM, ROM or FIFO. FIFO support includes dedicated FIFO pointer and flag “hard” control logic to minimize LUT use.

The MachXO registers in PFU and sysI/O can be configured to be SET or RESET. After power up and device is configured, the device enters into user mode with these registers SET/RESET according to the configuration setting, allowing device entering to a known state for predictable system function.

The MachXO architecture provides up to two sysCLOCK™ Phase Locked Loop (PLL) blocks on larger devices. These blocks are located at either end of the memory blocks. The PLLs have multiply, divide, and phase shifting capabilities that are used to manage the frequency and phase relationships of the clocks.

Every device in the family has a JTAG Port that supports programming and configuration of the device as well as access to the user logic. The MachXO devices are available for operation from 3.3V, 2.5V, 1.8V, and 1.2V power supplies, providing easy integration into the overall system.

**Figure 2-3. Top View of the MachXO256 Device**

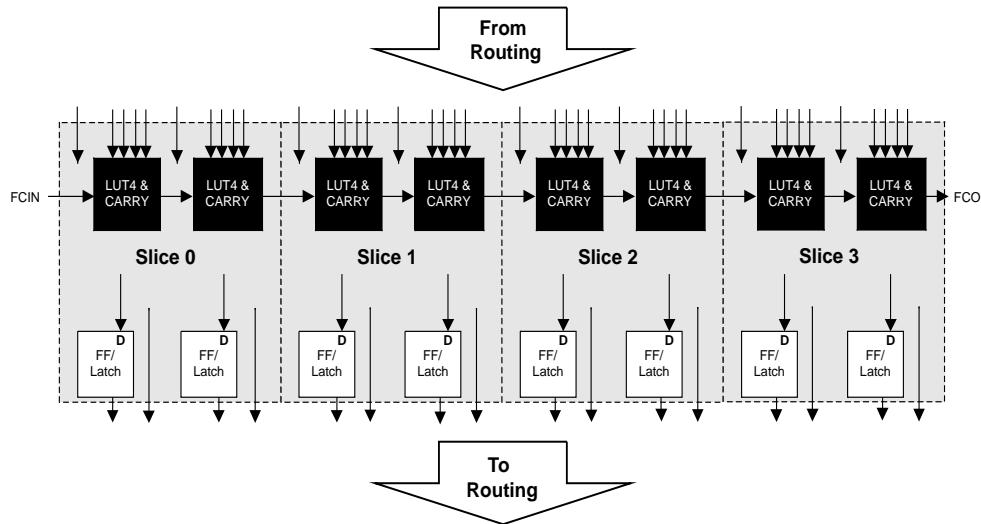


## PFU Blocks

The core of the MachXO devices consists of PFU and PFF blocks. The PFUs can be programmed to perform Logic, Arithmetic, Distributed RAM, and Distributed ROM functions. PFF blocks can be programmed to perform Logic, Arithmetic, and Distributed ROM functions. Except where necessary, the remainder of this data sheet will use the term PFU to refer to both PFU and PFF blocks.

Each PFU block consists of four interconnected Slices, numbered 0-3 as shown in Figure 2-4. There are 53 inputs and 25 outputs associated with each PFU block.

**Figure 2-4. PFU Diagram**

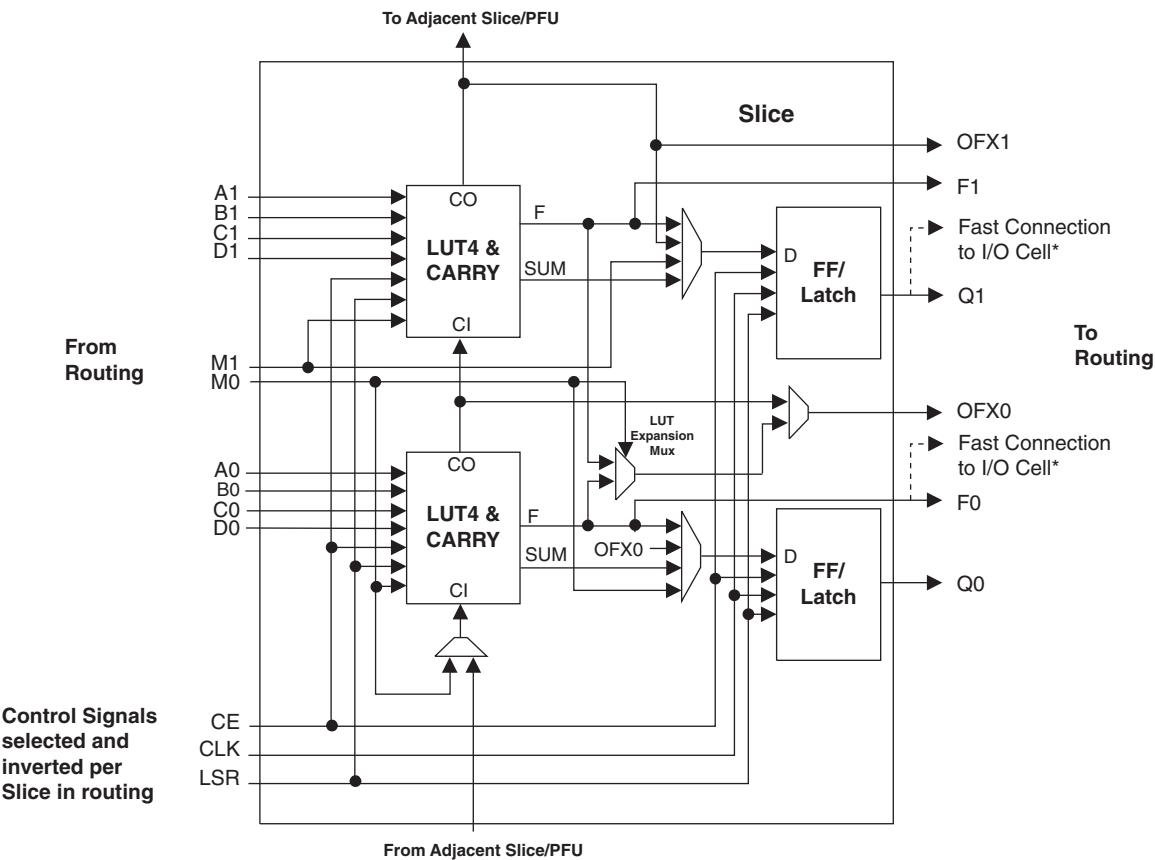


## Slice

Each Slice contains two LUT4 lookup tables feeding two registers (programmed to be in FF or Latch mode), and some associated logic that allows the LUTs to be combined to perform functions such as LUT5, LUT6, LUT7, and LUT8. There is control logic to perform set/reset functions (programmable as synchronous/asynchronous), clock select, chip-select, and wider RAM/ROM functions. Figure 2-5 shows an overview of the internal logic of the Slice. The registers in the Slice can be configured for positive/negative and edge/level clocks.

There are 14 input signals: 13 signals from routing and one from the carry-chain (from the adjacent Slice/PFU). There are 7 outputs: 6 to the routing and one to the carry-chain (to the adjacent Slice/PFU). Table 2-1 lists the signals associated with each Slice.

**Figure 2-5. Slice Diagram**



Notes:

Some inter-Slice signals are not shown.

\* Only PFUs at the edges have fast connections to the I/O cell.

**Table 2-1. Slice Signal Descriptions**

Function	Type	Signal Names	Description
Input	Data signal	A0, B0, C0, D0	Inputs to LUT4
Input	Data signal	A1, B1, C1, D1	Inputs to LUT4
Input	Multi-purpose	M0/M1	Multipurpose Input
Input	Control signal	CE	Clock Enable
Input	Control signal	LSR	Local Set/Reset
Input	Control signal	CLK	System Clock
Input	Inter-PFU signal	FCIN	Fast Carry In <sup>1</sup>
Output	Data signals	F0, F1	LUT4 output register bypass signals
Output	Data signals	Q0, Q1	Register Outputs
Output	Data signals	OFX0	Output of a LUT5 MUX
Output	Data signals	OFX1	Output of a LUT6, LUT7, LUT8 <sup>2</sup> MUX depending on the Slice
Output	Inter-PFU signal	FCO	Fast Carry Out <sup>1</sup>

1. See Figure 2-4 for connection details.

2. Requires two PFUs.

**Table 2-5. PLL Signal Descriptions**

Signal	I/O	Description
CLKI	I	Clock input from external pin or routing
CLKFB	I	PLL feedback input from PLL output, clock net, routing/external pin or internal feedback from CLKINTFB port
RST	I	"1" to reset the input clock divider
CLKOS	O	PLL output clock to clock tree (phase shifted/duty cycle changed)
CLKOP	O	PLL output clock to clock tree (No phase shift)
CLKOK	O	PLL output to clock tree through secondary clock divider
LOCK	O	"1" indicates PLL LOCK to CLKI
CLKINTFB	O	Internal feedback source, CLKOP divider output before CLOCKTREE
DDAMODE	I	Dynamic Delay Enable. "1": Pin control (dynamic), "0": Fuse Control (static)
DDAIZR	I	Dynamic Delay Zero. "1": delay = 0, "0": delay = on
DDAILAG	I	Dynamic Delay Lag/Lead. "1": Lag, "0": Lead
DDAIDEL[2:0]	I	Dynamic Delay Input

For more information on the PLL, please see details of additional technical documentation at the end of this data sheet.

## sysMEM Memory

The MachXO1200 and MachXO2280 devices contain sysMEM Embedded Block RAMs (EBRs). The EBR consists of a 9-Kbit RAM, with dedicated input and output registers.

### sysMEM Memory Block

The sysMEM block can implement single port, dual port, pseudo dual port, or FIFO memories. Each block can be used in a variety of depths and widths as shown in Table 2-6.

**Table 2-6. sysMEM Block Configurations**

Memory Mode	Configurations
Single Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18 256 x 36
True Dual Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18
Pseudo Dual Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18 256 x 36
FIFO	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18 256 x 36

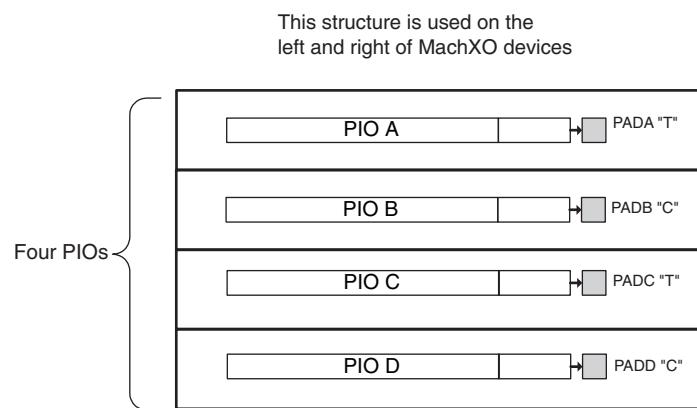
## PIO Groups

On the MachXO devices, PIO cells are assembled into two different types of PIO groups, those with four PIO cells and those with six PIO cells. PIO groups with four IOs are placed on the left and right sides of the device while PIO groups with six IOs are placed on the top and bottom. The individual PIO cells are connected to their respective sysIO buffers and PADs.

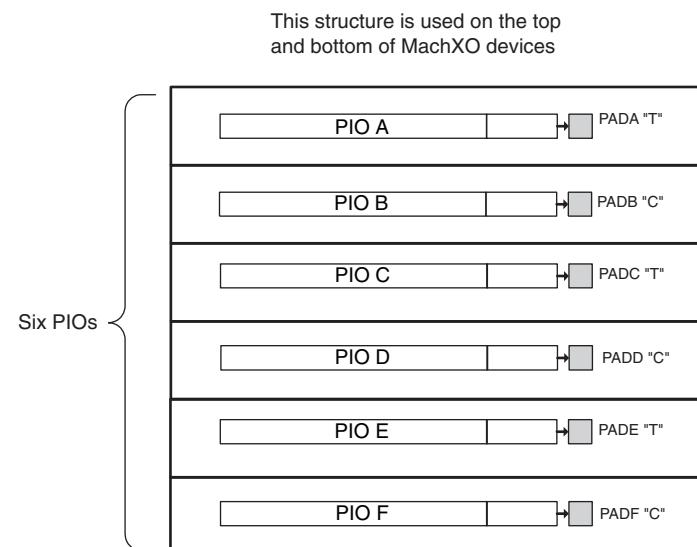
On all MachXO devices, two adjacent PIOs can be joined to provide a complementary Output driver pair. The I/O pin pairs are labeled as "T" and "C" to distinguish between the true and complement pins.

The MachXO1200 and MachXO2280 devices contain enhanced I/O capability. All PIO pairs on these larger devices can implement differential receivers. In addition, half of the PIO pairs on the left and right sides of these devices can be configured as LVDS transmit/receive pairs. PIOs on the top of these larger devices also provide PCI support.

**Figure 2-15. Group of Four Programmable I/O Cells**



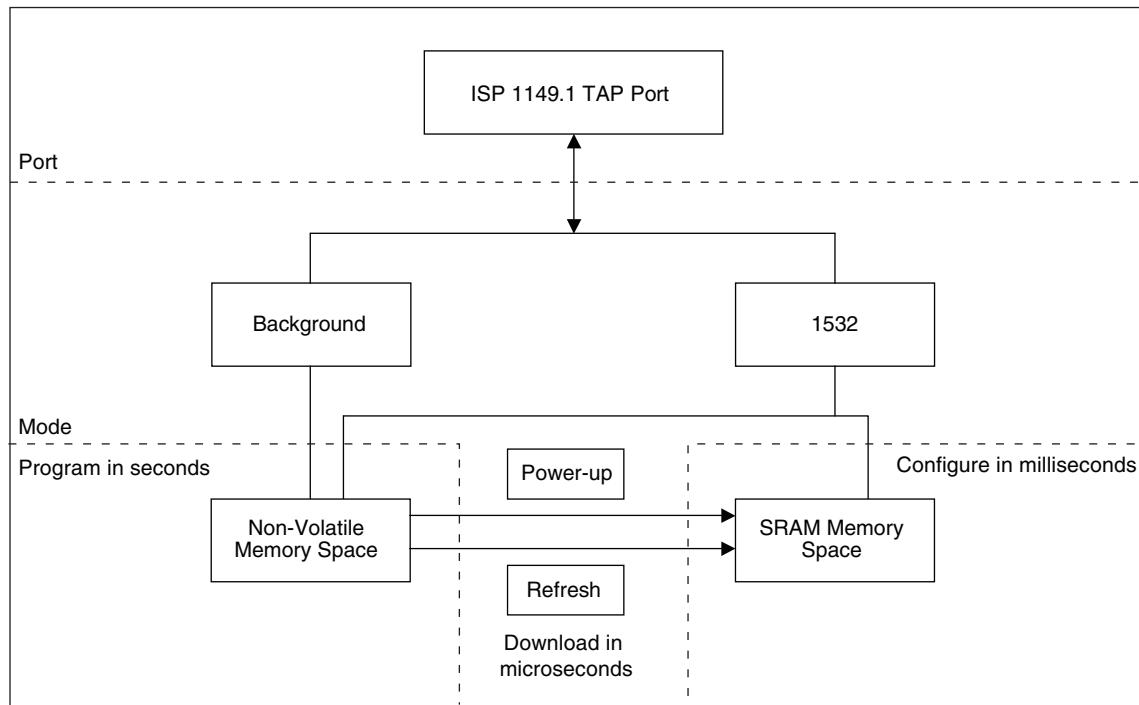
**Figure 2-16. Group of Six Programmable I/O Cells**



## PIO

The PIO blocks provide the interface between the sysIO buffers and the internal PFU array blocks. These blocks receive output data from the PFU array and a fast output data signal from adjacent PFUs. The output data and fast

**Figure 2-22. MachXO Configuration and Programming**



## Density Shifting

The MachXO family has been designed to enable density migration in the same package. Furthermore, the architecture ensures a high success rate when performing design migration from lower density parts to higher density parts. In many cases, it is also possible to shift a lower utilization design targeted for a high-density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case.

## Supply Current (Sleep Mode)<sup>1,2</sup>

Symbol	Parameter	Device	Typ. <sup>3</sup>	Max.	Units
$I_{CC}$	Core Power Supply	LCMxo256C	12	25	$\mu A$
		LCMxo640C	12	25	$\mu A$
		LCMxo1200C	12	25	$\mu A$
		LCMxo2280C	12	25	$\mu A$
$I_{CCAUX}$	Auxiliary Power Supply	LCMxo256C	1	15	$\mu A$
		LCMxo640C	1	25	$\mu A$
		LCMxo1200C	1	45	$\mu A$
		LCMxo2280C	1	85	$\mu A$
$I_{CCIO}$	Bank Power Supply <sup>4</sup>	All LCMxo 'C' Devices	2	30	$\mu A$

1. Assumes all inputs are configured as LVCMOS and held at the VCCIO or GND.

2. Frequency = 0MHz.

3.  $T_A = 25^\circ C$ , power supplies at nominal voltage.

4. Per Bank.

## Supply Current (Standby)<sup>1, 2, 3, 4</sup>

### Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ. <sup>5</sup>	Units
$I_{CC}$	Core Power Supply	LCMxo256C	7	mA
		LCMxo640C	9	mA
		LCMxo1200C	14	mA
		LCMxo2280C	20	mA
		LCMxo256E	4	mA
		LCMxo640E	6	mA
		LCMxo1200E	10	mA
		LCMxo2280E	12	mA
$I_{CCAUX}$	Auxiliary Power Supply $V_{CCAUX} = 3.3V$	LCMxo256E/C	5	mA
		LCMxo640E/C	7	mA
		LCMxo1200E/C	12	mA
		LCMxo2280E/C	13	mA
$I_{CCIO}$	Bank Power Supply <sup>6</sup>	All devices	2	mA

1. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.

2. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at  $V_{CCIO}$  or GND.

3. Frequency = 0MHz.

4. User pattern = blank.

5.  $T_J = 25^\circ C$ , power supplies at nominal voltage.

6. Per Bank.  $V_{CCIO} = 2.5V$ . Does not include pull-up/pull-down.

## Typical Building Block Function Performance<sup>1</sup>

### Pin-to-Pin Performance (LVCMS25 12mA Drive)

Function	-5 Timing	Units
<b>Basic Functions</b>		
16-bit decoder	6.7	ns
4:1 MUX	4.5	ns
16:1 MUX	5.1	ns

### Register-to-Register Performance

Function	-5 Timing	Units
<b>Basic Functions</b>		
16:1 MUX	487	MHz
16-bit adder	292	MHz
16-bit counter	388	MHz
64-bit counter	200	MHz
<b>Embedded Memory Functions (1200 and 2280 Devices Only)</b>		
256x36 Single Port RAM	284	MHz
512x18 True-Dual Port RAM	284	MHz
<b>Distributed Memory Functions</b>		
16x2 Single Port RAM	434	MHz
64x2 Single Port RAM	320	MHz
128x4 Single Port RAM	261	MHz
32x2 Pseudo-Dual Port RAM	314	MHz
64x4 Pseudo-Dual Port RAM	271	MHz

1. The above timing numbers are generated using the ispLEVER design tool. Exact performance may vary with device and tool version. The tool uses internal parameters that have been characterized but are not tested on every device.

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### Derating Logic Timing

Logic Timing provided in the following sections of the data sheet and the ispLEVER design tools are worst case numbers in the operating range. Actual delays may be much faster. The ispLEVER design tool from Lattice can provide logic timing numbers at a particular temperature and voltage.

## MachXO Internal Timing Parameters<sup>1</sup>

Over Recommended Operating Conditions

Parameter	Description	-5		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
<b>PFU/PFF Logic Mode Timing</b>								
t <sub>LUT4_PFU</sub>	LUT4 delay (A to D inputs to F output)	—	0.28	—	0.34	—	0.39	ns
t <sub>LUT6_PFU</sub>	LUT6 delay (A to D inputs to OFX output)	—	0.44	—	0.53	—	0.62	ns
t <sub>LSR_PFU</sub>	Set/Reset to output of PFU	—	0.90	—	1.08	—	1.26	ns
t <sub>SUM_PFU</sub>	Clock to Mux (M0,M1) input setup time	0.10	—	0.13	—	0.15	—	ns
t <sub>HM_PFU</sub>	Clock to Mux (M0,M1) input hold time	-0.05	—	-0.06	—	-0.07	—	ns
t <sub>SUD_PFU</sub>	Clock to D input setup time	0.13	—	0.16	—	0.18	—	ns
t <sub>HD_PFU</sub>	Clock to D input hold time	-0.03	—	-0.03	—	-0.04	—	ns
t <sub>CK2Q_PFU</sub>	Clock to Q delay, D-type register configuration	—	0.40	—	0.48	—	0.56	ns
t <sub>LE2Q_PFU</sub>	Clock to Q delay latch configuration	—	0.53	—	0.64	—	0.74	ns
t <sub>LD2Q_PFU</sub>	D to Q throughput delay when latch is enabled	—	0.55	—	0.66	—	0.77	ns
<b>PFU Dual Port Memory Mode Timing</b>								
t <sub>CORAM_PFU</sub>	Clock to Output	—	0.40	—	0.48	—	0.56	ns
t <sub>SUDATA_PFU</sub>	Data Setup Time	-0.18	—	-0.22	—	-0.25	—	ns
t <sub>HDATA_PFU</sub>	Data Hold Time	0.28	—	0.34	—	0.39	—	ns
t <sub>SUADDR_PFU</sub>	Address Setup Time	-0.46	—	-0.56	—	-0.65	—	ns
t <sub>HADDR_PFU</sub>	Address Hold Time	0.71	—	0.85	—	0.99	—	ns
t <sub>SUWREN_PFU</sub>	Write/Read Enable Setup Time	-0.22	—	-0.26	—	-0.30	—	ns
t <sub>HWREN_PFU</sub>	Write/Read Enable Hold Time	0.33	—	0.40	—	0.47	—	ns
<b>PIO Input/Output Buffer Timing</b>								
t <sub>IN_PIO</sub>	Input Buffer Delay	—	0.75	—	0.90	—	1.06	ns
t <sub>OUT_PIO</sub>	Output Buffer Delay	—	1.29	—	1.54	—	1.80	ns
<b>EBR Timing (1200 and 2280 Devices Only)</b>								
t <sub>CO_EBR</sub>	Clock to output from Address or Data with no output register	—	2.24	—	2.69	—	3.14	ns
t <sub>COO_EBR</sub>	Clock to output from EBR output Register	—	0.54	—	0.64	—	0.75	ns
t <sub>SUDATA_EBR</sub>	Setup Data to EBR Memory	-0.26	—	-0.31	—	-0.37	—	ns
t <sub>HDATA_EBR</sub>	Hold Data to EBR Memory	0.41	—	0.49	—	0.57	—	ns
t <sub>SUADDR_EBR</sub>	Setup Address to EBR Memory	-0.26	—	-0.31	—	-0.37	—	ns
t <sub>HADDR_EBR</sub>	Hold Address to EBR Memory	0.41	—	0.49	—	0.57	—	ns
t <sub>SUWREN_EBR</sub>	Setup Write/Read Enable to EBR Memory	-0.17	—	-0.20	—	-0.23	—	ns
t <sub>HWREN_EBR</sub>	Hold Write/Read Enable to EBR Memory	0.26	—	0.31	—	0.36	—	ns
t <sub>SUCE_EBR</sub>	Clock Enable Setup Time to EBR Output Register	0.19	—	0.23	—	0.27	—	ns
t <sub>HCE_EBR</sub>	Clock Enable Hold Time to EBR Output Register	-0.13	—	-0.16	—	-0.18	—	ns
t <sub>RSTO_EBR</sub>	Reset To Output Delay Time from EBR Output Register	—	1.03	—	1.23	—	1.44	ns
<b>PLL Parameters (1200 and 2280 Devices Only)</b>								
t <sub>RSTREC</sub>	Reset Recovery to Rising Clock	1.00	—	1.00	—	1.00	—	ns
t <sub>RSTSU</sub>	Reset Signal Setup Time	1.00	—	1.00	—	1.00	—	ns

1. Internal parameters are characterized but not tested on every device.

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## MachXO Family Timing Adders<sup>1, 2, 3</sup>

**Over Recommended Operating Conditions**

Buffer Type	Description	-5	-4	-3	Units
<b>Input Adjusters</b>					
LVDS25 <sup>4</sup>	LVDS	0.44	0.53	0.61	ns
BLVDS25 <sup>4</sup>	BLVDS	0.44	0.53	0.61	ns
LVPECL33 <sup>4</sup>	LVPECL	0.42	0.50	0.59	ns
LVTTL33	LVTTL	0.01	0.01	0.01	ns
LVCMOS33	LVCMOS 3.3	0.01	0.01	0.01	ns
LVCMOS25	LVCMOS 2.5	0.00	0.00	0.00	ns
LVCMOS18	LVCMOS 1.8	0.07	0.08	0.10	ns
LVCMOS15	LVCMOS 1.5	0.14	0.17	0.19	ns
LVCMOS12	LVCMOS 1.2	0.40	0.48	0.56	ns
PCI33 <sup>4</sup>	PCI	0.01	0.01	0.01	ns
<b>Output Adjusters</b>					
LVDS25E	LVDS 2.5 E	-0.13	-0.15	-0.18	ns
LVDS25 <sup>4</sup>	LVDS 2.5	-0.21	-0.26	-0.30	ns
BLVDS25	BLVDS 2.5	-0.03	-0.03	-0.04	ns
LVPECL33	LVPECL 3.3	0.04	0.04	0.05	ns
LVTTL33_4mA	LVTTL 4mA drive	0.04	0.04	0.05	ns
LVTTL33_8mA	LVTTL 8mA drive	0.06	0.07	0.08	ns
LVTTL33_12mA	LVTTL 12mA drive	-0.01	-0.01	-0.01	ns
LVTTL33_16mA	LVTTL 16mA drive	0.50	0.60	0.70	ns
LVCMOS33_4mA	LVCMOS 3.3 4mA drive	0.04	0.04	0.05	ns
LVCMOS33_8mA	LVCMOS 3.3 8mA drive	0.06	0.07	0.08	ns
LVCMOS33_12mA	LVCMOS 3.3 12mA drive	-0.01	-0.01	-0.01	ns
LVCMOS33_14mA	LVCMOS 3.3 14mA drive	0.50	0.60	0.70	ns
LVCMOS25_4mA	LVCMOS 2.5 4mA drive	0.05	0.06	0.07	ns
LVCMOS25_8mA	LVCMOS 2.5 8mA drive	0.10	0.12	0.13	ns
LVCMOS25_12mA	LVCMOS 2.5 12mA drive	0.00	0.00	0.00	ns
LVCMOS25_14mA	LVCMOS 2.5 14mA drive	0.34	0.40	0.47	ns
LVCMOS18_4mA	LVCMOS 1.8 4mA drive	0.11	0.13	0.15	ns
LVCMOS18_8mA	LVCMOS 1.8 8mA drive	0.05	0.06	0.06	ns
LVCMOS18_12mA	LVCMOS 1.8 12mA drive	-0.06	-0.07	-0.08	ns
LVCMOS18_14mA	LVCMOS 1.8 14mA drive	0.06	0.07	0.09	ns
LVCMOS15_4mA	LVCMOS 1.5 4mA drive	0.15	0.19	0.22	ns
LVCMOS15_8mA	LVCMOS 1.5 8mA drive	0.05	0.06	0.07	ns
LVCMOS12_2mA	LVCMOS 1.2 2mA drive	0.26	0.31	0.36	ns
LVCMOS12_6mA	LVCMOS 1.2 6mA drive	0.05	0.06	0.07	ns
PCI33 <sup>4</sup>	PCI33	1.85	2.22	2.59	ns

1. Timing adders are characterized but not tested on every device.
2. LVCMOS timing is measured with the load specified in Switching Test Conditions table.
3. All other standards tested according to the appropriate specifications.
4. I/O standard only available in LCMXO1200 and LCMXO2280 devices.

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## sysCLOCK PLL Timing

### Over Recommended Operating Conditions

Parameter	Descriptions	Conditions	Min.	Max.	Units
$f_{IN}$	Input Clock Frequency (CLKI, CLKFB)		25	420	MHz
		Input Divider (M) = 1; Feedback Divider (N) <= 4 <sup>5, 6</sup>	18	25	MHz
$f_{OUT}$	Output Clock Frequency (CLKOP, CLKOS)		25	420	MHz
$f_{OUT2}$	K-Divider Output Frequency (CLKOK)		0.195	210	MHz
$f_{VCO}$	PLL VCO Frequency		420	840	MHz
$f_{PFD}$	Phase Detector Input Frequency		25	—	MHz
		Input Divider (M) = 1; Feedback Divider (N) <= 4 <sup>5, 6</sup>	18	25	MHz
<b>AC Characteristics</b>					
$t_{DT}$	Output Clock Duty Cycle	Default duty cycle selected <sup>3</sup>	45	55	%
$t_{PH}^4$	Output Phase Accuracy		—	0.05	UI
$t_{OPJIT}^1$	Output Clock Period Jitter	$f_{OUT} \geq 100$ MHz	—	+/-120	ps
		$f_{OUT} < 100$ MHz	—	0.02	UIPP
$t_{SK}$	Input Clock to Output Clock Skew	Divider ratio = integer	—	+/-200	ps
$t_W$	Output Clock Pulse Width	At 90% or 10% <sup>3</sup>	1	—	ns
$t_{LOCK}^2$	PLL Lock-in Time		—	150	μs
$t_{PA}$	Programmable Delay Unit		100	450	ps
$t_{IPJIT}$	Input Clock Period Jitter	$f_{OUT} \geq 100$ MHz	—	+/-200	ps
		$f_{OUT} < 100$ MHz	—	0.02	UI
$t_{FBKDLY}$	External Feedback Delay		—	10	ns
$t_{HI}$	Input Clock High Time	90% to 90%	0.5	—	ns
$t_{LO}$	Input Clock Low Time	10% to 10%	0.5	—	ns
$t_{RST}$	RST Pulse Width		10	—	ns

1. Jitter sample is taken over 10,000 samples of the primary PLL output with a clean reference clock.

2. Output clock is valid after  $t_{LOCK}$  for PLL reset and dynamic delay adjustment.

3. Using LVDS output buffers.

4. CLKOS as compared to CLKOP output.

5. When using an input frequency less than 25 MHz the output frequency must be less than or equal to 4 times the input frequency.

6. The on-chip oscillator can be used to provide reference clock input to the PLL provided the output frequency restriction for clock inputs below 25 MHz are followed.

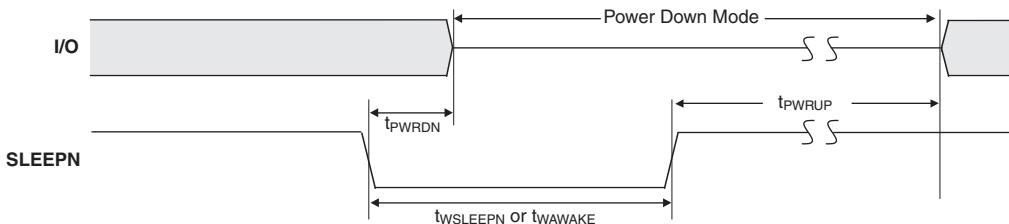
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## MachXO "C" Sleep Mode Timing

Symbol	Parameter	Device	Min.	Typ.	Max	Units
$t_{PWRDN}$	SLEEPN Low to Power Down	All	—	—	400	ns
$t_{PWRUP}$	SLEEPN High to Power Up	LCMXO256	—	—	400	μs
		LCMXO640	—	—	600	μs
		LCMXO1200	—	—	800	μs
		LCMXO2280	—	—	1000	μs
$t_{WSLEEPN}$	SLEEPN Pulse Width	All	400	—	—	ns
$t_{WAWAKE}$	SLEEPN Pulse Rejection	All	—	—	100	ns

Rev. A 0.19

## Flash Download Time



Symbol	Parameter	Min.	Typ.	Max.	Units	
$t_{REFRESH}$	Minimum $V_{CC}$ or $V_{CCAUX}$ (later of the two supplies) to Device I/O Active	LCMXO256	—	—	0.4	ms
		LCMXO640	—	—	0.6	ms
		LCMXO1200	—	—	0.8	ms
		LCMXO2280	—	—	1.0	ms

## JTAG Port Timing Specifications

Symbol	Parameter	Min.	Max.	Units
$f_{MAX}$	TCK [BSCAN] clock frequency	—	25	MHz
$t_{BTCP}$	TCK [BSCAN] clock pulse width	40	—	ns
$t_{BTCPH}$	TCK [BSCAN] clock pulse width high	20	—	ns
$t_{BTCPL}$	TCK [BSCAN] clock pulse width low	20	—	ns
$t_{BTS}$	TCK [BSCAN] setup time	8	—	ns
$t_{BTH}$	TCK [BSCAN] hold time	10	—	ns
$t_{BTRF}$	TCK [BSCAN] rise/fall time	50	—	mV/ns
$t_{BTCO}$	TAP controller falling edge of clock to output valid	—	10	ns
$t_{BTCODIS}$	TAP controller falling edge of clock to output disabled	—	10	ns
$t_{BTCOEN}$	TAP controller falling edge of clock to output enabled	—	10	ns
$t_{BTCRS}$	BSCAN test capture register setup time	8	—	ns
$t_{BTCRH}$	BSCAN test capture register hold time	25	—	ns
$t_{BUTCO}$	BSCAN test update register, falling edge of clock to output valid	—	25	ns
$t_{BTUODIS}$	BSCAN test update register, falling edge of clock to output disabled	—	25	ns
$t_{BTUOPEN}$	BSCAN test update register, falling edge of clock to output enabled	—	25	ns

Rev. A 0.19

**LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections:  
 132 csBGA (Cont.)**

LCMXO640					LCMXO1200					LCMXO2280				
Ball #	Ball Function	Bank	Dual Function	Differential	Ball #	Ball Function	Bank	Dual Function	Differential	Ball #	Ball Function	Bank	Dual Function	Differential
B9	PT7B	0		C	B9	PT9B	1		C	B9	PT12D	1		C
A9	PT7A	0		T	A9	PT9A	1		T	A9	PT12C	1		T
A8	PT6B	0	PCLK0_1***	C	A8	PT7D	1	PCLK1_1***		A8	PT10B	1	PCLK1_1***	
B8	PT6A	0		T	B8	PT7B	1			B8	PT9D	1		
C8	PT5B	0	PCLK0_0***	C	C8	PT6F	0	PCLK1_0***		C8	PT9B	1	PCLK1_0***	
B7	PT5A	0		T	B7	PT6D	0			B7	PT8D	0		
A7	VCCAUX	-			A7	VCCAUX	-			A7	VCCAUX	-		
C7	VCC	-			C7	VCC	-			C7	VCC	-		
A6	PT4D	0		C	A6	PT5D	0		C	A6	PT7B	0		C
B6	PT4C	0		T	B6	PT5C	0		T	B6	PT7A	0		T
C6	PT3F	0		C	C6	PT5B	0		C	C6	PT6D	0		
B5	PT3E	0		T	B5	PT5A	0		T	B5	PT6E	0		T
A5	PT3D	0			A5	PT4B	0			A5	PT6F	0		C
B4	GNDIO0	0			B4	GNDIO0	0			B4	GNDIO0	0		
A4	PT3B	0			A4	PT3D	0		C	A4	PT4B	0		C
C4	PT2F	0			C4	PT3C	0		T	C4	PT4A	0		T
A3	PT2D	0		C	A3	PT3B	0		C	A3	PT3B	0		C
A2	PT2C	0		T	A2	PT2B	0		C	A2	PT2B	0		C
B3	PT2B	0		C	B3	PT3A	0		T	B3	PT3A	0		T
A1	PT2A	0		T	A1	PT2A	0		T	A1	PT2A	0		T
F1	GND	-			F1	GND	-			F1	GND	-		
P9	GND	-			P9	GND	-			P9	GND	-		
J14	GND	-			J14	GND	-			J14	GND	-		
C9	GND	-			C9	GND	-			C9	GND	-		
C5	VCCIO0	0			C5	VCCIO0	0			C5	VCCIO0	0		
B11	VCCIO0	0			B11	VCCIO1	1			B11	VCCIO1	1		
E12	VCCIO1	1			E12	VCCIO2	2			E12	VCCIO2	2		
L12	VCCIO1	1			L12	VCCIO3	3			L12	VCCIO3	3		
M10	VCCIO2	2			M10	VCCIO4	4			M10	VCCIO4	4		
N2	VCCIO2	2			N2	VCCIO5	5			N2	VCCIO5	5		
D2	VCCIO3	3			D2	VCCIO7	7			D2	VCCIO7	7		
K3	VCCIO3	3			K3	VCCIO6	6			K3	VCCIO6	6		

\*Supports true LVDS outputs.

\*\*NC for "E" devices.

\*\*\*Primary clock inputs are single-ended.

**LCMxo640, LCMxo1200 and LCMxo2280 Logic Signal Connections:  
 144 TQFP (Cont.)**

Pin Number	LCMxo640				LCMxo1200				LCMxo2280			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
51	TDI	2	TDI		TDI	5	TDI		TDI	5	TDI	
52	VCC	-			VCC	-			VCC	-		
53	VCCAUX	-			VCCAUX	-			VCCAUX	-		
54	PB5A	2		T	PB6F	5			PB8F	5		
55	PB5B	2	PCLKT2_1***	C	PB7B	4	PCLK4_1***		PB10F	4	PCLK4_1***	
56	PB5D	2			PB7C	4			PB10C	4		T
57	PB6A	2		T	PB7D	4			PB10D	4		C
58	PB6B	2	PCLKT2_0***	C	PB7F	4	PCLK4_0***		PB10B	4	PCLK4_0***	
59	GND	-			GND	-			GND	-		
60	PB7C	2			PB9A	4			PB12A	4		T
61	PB7E	2			PB9B	4			PB12B	4		C
62	PB8A	2			PB9E	4			PB12E	4		
63	VCCIO2	2			VCCIO4	4			VCCIO4	4		
64	GNDIO2	2			GNDIO4	4			GNDIO4	4		
65	PB8C	2		T	PB10A	4			PB13A	4		T
66	PB8D	2		C	PB10B	4			PB13B	4		C
67	PB9A	2		T	PB10C	4			PB13C	4		T
68	PB9C	2		T	PB10D	4			PB13D	4		C
69	PB9B	2		C	PB10F	4			PB14D	4		
70**	SLEEPN	-	SLEEPN		SLEEPN	-	SLEEPN		SLEEPN	-	SLEEPN	
71	PB9D	2		C	PB11C	4			PB16C	4		T
72	PB9F	2			PB11D	4			PB16D	4		C
73	PR11D	1		C	PR16B	3			PR20B	3		C
74	PR11B	1		C	PR16A	3			PR20A	3		T
75	PR11C	1		T	PR15B	3			PR19B	3		C
76	PR10D	1		C	PR15A	3			PR19A	3		T
77	PR11A	1		T	PR14D	3			PR17D	3		C
78	PR10B	1		C	PR14C	3			PR17C	3		T
79	PR10C	1		T	PR14B	3			PR17B	3		C*
80	PR10A	1		T	PR14A	3			PR17A	3		T*
81	PR9D	1			PR13D	3			PR16D	3		
82	VCCIO1	1			VCCIO3	3			VCCIO3	3		
83	GNDIO1	1			GNDIO3	3			GNDIO3	3		
84	PR9A	1			PR12B	3			PR15B	3		C*
85	PR8C	1			PR12A	3			PR15A	3		T*
86	PR8A	1			PR11B	3			PR14B	3		C*
87	PR7D	1			PR11A	3			PR14A	3		T*
88	GND	-			GND	-			GND	-		
89	PR7B	1		C	PR10B	3			PR13B	3		C*
90	PR7A	1		T	PR10A	3			PR13A	3		T*
91	PR6D	1		C	PR8B	2			PR10B	2		C*
92	PR6C	1		T	PR8A	2			PR10A	2		T*
93	VCC	-			VCC	-			VCC	-		
94	PR5D	1			PR6B	2			PR8B	2		C*
95	PR5B	1			PR6A	2			PR8A	2		T*
96	PR4D	1			PR5B	2			PR7B	2		C*
97	PR4B	1		C	PR5A	2			PR7A	2		T*
98	VCCIO1	1			VCCIO2	2			VCCIO2	2		
99	GNDIO1	1			GNDIO2	2			GNDIO2	2		
100	PR4A	1		T	PR4C	2			PR5C	2		

## Conventional Packaging

### Commercial

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo256C-3T100C	256	1.8V/2.5V/3.3V	78	-3	TQFP	100	COM
LCMxo256C-4T100C	256	1.8V/2.5V/3.3V	78	-4	TQFP	100	COM
LCMxo256C-5T100C	256	1.8V/2.5V/3.3V	78	-5	TQFP	100	COM
LCMxo256C-3M100C	256	1.8V/2.5V/3.3V	78	-3	csBGA	100	COM
LCMxo256C-4M100C	256	1.8V/2.5V/3.3V	78	-4	csBGA	100	COM
LCMxo256C-5M100C	256	1.8V/2.5V/3.3V	78	-5	csBGA	100	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo640C-3T100C	640	1.8V/2.5V/3.3V	74	-3	TQFP	100	COM
LCMxo640C-4T100C	640	1.8V/2.5V/3.3V	74	-4	TQFP	100	COM
LCMxo640C-5T100C	640	1.8V/2.5V/3.3V	74	-5	TQFP	100	COM
LCMxo640C-3M100C	640	1.8V/2.5V/3.3V	74	-3	csBGA	100	COM
LCMxo640C-4M100C	640	1.8V/2.5V/3.3V	74	-4	csBGA	100	COM
LCMxo640C-5M100C	640	1.8V/2.5V/3.3V	74	-5	csBGA	100	COM
LCMxo640C-3T144C	640	1.8V/2.5V/3.3V	113	-3	TQFP	144	COM
LCMxo640C-4T144C	640	1.8V/2.5V/3.3V	113	-4	TQFP	144	COM
LCMxo640C-5T144C	640	1.8V/2.5V/3.3V	113	-5	TQFP	144	COM
LCMxo640C-3M132C	640	1.8V/2.5V/3.3V	101	-3	csBGA	132	COM
LCMxo640C-4M132C	640	1.8V/2.5V/3.3V	101	-4	csBGA	132	COM
LCMxo640C-5M132C	640	1.8V/2.5V/3.3V	101	-5	csBGA	132	COM
LCMxo640C-3B256C	640	1.8V/2.5V/3.3V	159	-3	caBGA	256	COM
LCMxo640C-4B256C	640	1.8V/2.5V/3.3V	159	-4	caBGA	256	COM
LCMxo640C-5B256C	640	1.8V/2.5V/3.3V	159	-5	caBGA	256	COM
LCMxo640C-3FT256C	640	1.8V/2.5V/3.3V	159	-3	ftBGA	256	COM
LCMxo640C-4FT256C	640	1.8V/2.5V/3.3V	159	-4	ftBGA	256	COM
LCMxo640C-5FT256C	640	1.8V/2.5V/3.3V	159	-5	ftBGA	256	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo1200C-3T100C	1200	1.8V/2.5V/3.3V	73	-3	TQFP	100	COM
LCMxo1200C-4T100C	1200	1.8V/2.5V/3.3V	73	-4	TQFP	100	COM
LCMxo1200C-5T100C	1200	1.8V/2.5V/3.3V	73	-5	TQFP	100	COM
LCMxo1200C-3T144C	1200	1.8V/2.5V/3.3V	113	-3	TQFP	144	COM
LCMxo1200C-4T144C	1200	1.8V/2.5V/3.3V	113	-4	TQFP	144	COM
LCMxo1200C-5T144C	1200	1.8V/2.5V/3.3V	113	-5	TQFP	144	COM
LCMxo1200C-3M132C	1200	1.8V/2.5V/3.3V	101	-3	csBGA	132	COM
LCMxo1200C-4M132C	1200	1.8V/2.5V/3.3V	101	-4	csBGA	132	COM
LCMxo1200C-5M132C	1200	1.8V/2.5V/3.3V	101	-5	csBGA	132	COM
LCMxo1200C-3B256C	1200	1.8V/2.5V/3.3V	211	-3	caBGA	256	COM
LCMxo1200C-4B256C	1200	1.8V/2.5V/3.3V	211	-4	caBGA	256	COM
LCMxo1200C-5B256C	1200	1.8V/2.5V/3.3V	211	-5	caBGA	256	COM
LCMxo1200C-3FT256C	1200	1.8V/2.5V/3.3V	211	-3	ftBGA	256	COM
LCMxo1200C-4FT256C	1200	1.8V/2.5V/3.3V	211	-4	ftBGA	256	COM
LCMxo1200C-5FT256C	1200	1.8V/2.5V/3.3V	211	-5	ftBGA	256	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo2280C-3T100C	2280	1.8V/2.5V/3.3V	73	-3	TQFP	100	COM
LCMxo2280C-4T100C	2280	1.8V/2.5V/3.3V	73	-4	TQFP	100	COM
LCMxo2280C-5T100C	2280	1.8V/2.5V/3.3V	73	-5	TQFP	100	COM
LCMxo2280C-3T144C	2280	1.8V/2.5V/3.3V	113	-3	TQFP	144	COM
LCMxo2280C-4T144C	2280	1.8V/2.5V/3.3V	113	-4	TQFP	144	COM
LCMxo2280C-5T144C	2280	1.8V/2.5V/3.3V	113	-5	TQFP	144	COM
LCMxo2280C-3M132C	2280	1.8V/2.5V/3.3V	101	-3	csBGA	132	COM
LCMxo2280C-4M132C	2280	1.8V/2.5V/3.3V	101	-4	csBGA	132	COM
LCMxo2280C-5M132C	2280	1.8V/2.5V/3.3V	101	-5	csBGA	132	COM
LCMxo2280C-3B256C	2280	1.8V/2.5V/3.3V	211	-3	caBGA	256	COM
LCMxo2280C-4B256C	2280	1.8V/2.5V/3.3V	211	-4	caBGA	256	COM
LCMxo2280C-5B256C	2280	1.8V/2.5V/3.3V	211	-5	caBGA	256	COM
LCMxo2280C-3FT256C	2280	1.8V/2.5V/3.3V	211	-3	ftBGA	256	COM
LCMxo2280C-4FT256C	2280	1.8V/2.5V/3.3V	211	-4	ftBGA	256	COM
LCMxo2280C-5FT256C	2280	1.8V/2.5V/3.3V	211	-5	ftBGA	256	COM
LCMxo2280C-3FT324C	2280	1.8V/2.5V/3.3V	271	-3	ftBGA	324	COM
LCMxo2280C-4FT324C	2280	1.8V/2.5V/3.3V	271	-4	ftBGA	324	COM
LCMxo2280C-5FT324C	2280	1.8V/2.5V/3.3V	271	-5	ftBGA	324	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo256E-3T100C	256	1.2V	78	-3	TQFP	100	COM
LCMxo256E-4T100C	256	1.2V	78	-4	TQFP	100	COM
LCMxo256E-5T100C	256	1.2V	78	-5	TQFP	100	COM
LCMxo256E-3M100C	256	1.2V	78	-3	csBGA	100	COM
LCMxo256E-4M100C	256	1.2V	78	-4	csBGA	100	COM
LCMxo256E-5M100C	256	1.2V	78	-5	csBGA	100	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo640E-3T100C	640	1.2V	74	-3	TQFP	100	COM
LCMxo640E-4T100C	640	1.2V	74	-4	TQFP	100	COM
LCMxo640E-5T100C	640	1.2V	74	-5	TQFP	100	COM
LCMxo640E-3M100C	640	1.2V	74	-3	csBGA	100	COM
LCMxo640E-4M100C	640	1.2V	74	-4	csBGA	100	COM
LCMxo640E-5M100C	640	1.2V	74	-5	csBGA	100	COM
LCMxo640E-3T144C	640	1.2V	113	-3	TQFP	144	COM
LCMxo640E-4T144C	640	1.2V	113	-4	TQFP	144	COM
LCMxo640E-5T144C	640	1.2V	113	-5	TQFP	144	COM
LCMxo640E-3M132C	640	1.2V	101	-3	csBGA	132	COM
LCMxo640E-4M132C	640	1.2V	101	-4	csBGA	132	COM
LCMxo640E-5M132C	640	1.2V	101	-5	csBGA	132	COM
LCMxo640E-3B256C	640	1.2V	159	-3	caBGA	256	COM
LCMxo640E-4B256C	640	1.2V	159	-4	caBGA	256	COM
LCMxo640E-5B256C	640	1.2V	159	-5	caBGA	256	COM
LCMxo640E-3FT256C	640	1.2V	159	-3	ftBGA	256	COM
LCMxo640E-4FT256C	640	1.2V	159	-4	ftBGA	256	COM
LCMxo640E-5FT256C	640	1.2V	159	-5	ftBGA	256	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo256E-3T100I	256	1.2V	78	-3	TQFP	100	IND
LCMxo256E-4T100I	256	1.2V	78	-4	TQFP	100	IND
LCMxo256E-3M100I	256	1.2V	78	-3	csBGA	100	IND
LCMxo256E-4M100I	256	1.2V	78	-4	csBGA	100	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo640E-3T100I	640	1.2V	74	-3	TQFP	100	IND
LCMxo640E-4T100I	640	1.2V	74	-4	TQFP	100	IND
LCMxo640E-3M100I	640	1.2V	74	-3	csBGA	100	IND
LCMxo640E-4M100I	640	1.2V	74	-4	csBGA	100	IND
LCMxo640E-3T144I	640	1.2V	113	-3	TQFP	144	IND
LCMxo640E-4T144I	640	1.2V	113	-4	TQFP	144	IND
LCMxo640E-3M132I	640	1.2V	101	-3	csBGA	132	IND
LCMxo640E-4M132I	640	1.2V	101	-4	csBGA	132	IND
LCMxo640E-3B256I	640	1.2V	159	-3	caBGA	256	IND
LCMxo640E-4B256I	640	1.2V	159	-4	caBGA	256	IND
LCMxo640E-3FT256I	640	1.2V	159	-3	ftBGA	256	IND
LCMxo640E-4FT256I	640	1.2V	159	-4	ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo1200E-3T100I	1200	1.2V	73	-3	TQFP	100	IND
LCMxo1200E-4T100I	1200	1.2V	73	-4	TQFP	100	IND
LCMxo1200E-3T144I	1200	1.2V	113	-3	TQFP	144	IND
LCMxo1200E-4T144I	1200	1.2V	113	-4	TQFP	144	IND
LCMxo1200E-3M132I	1200	1.2V	101	-3	csBGA	132	IND
LCMxo1200E-4M132I	1200	1.2V	101	-4	csBGA	132	IND
LCMxo1200E-3B256I	1200	1.2V	211	-3	caBGA	256	IND
LCMxo1200E-4B256I	1200	1.2V	211	-4	caBGA	256	IND
LCMxo1200E-3FT256I	1200	1.2V	211	-3	ftBGA	256	IND
LCMxo1200E-4FT256I	1200	1.2V	211	-4	ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo2280E-3T100I	2280	1.2V	73	-3	TQFP	100	IND
LCMxo2280E-4T100I	2280	1.2V	73	-4	TQFP	100	IND
LCMxo2280E-3T144I	2280	1.2V	113	-3	TQFP	144	IND
LCMxo2280E-4T144I	2280	1.2V	113	-4	TQFP	144	IND
LCMxo2280E-3M132I	2280	1.2V	101	-3	csBGA	132	IND
LCMxo2280E-4M132I	2280	1.2V	101	-4	csBGA	132	IND
LCMxo2280E-3B256I	2280	1.2V	211	-3	caBGA	256	IND
LCMxo2280E-4B256I	2280	1.2V	211	-4	caBGA	256	IND
LCMxo2280E-3FT256I	2280	1.2V	211	-3	ftBGA	256	IND
LCMxo2280E-4FT256I	2280	1.2V	211	-4	ftBGA	256	IND
LCMxo2280E-3FT324I	2280	1.2V	271	-3	ftBGA	324	IND
LCMxo2280E-4FT324I	2280	1.2V	271	-4	ftBGA	324	IND

**Lead-Free Packaging**
**Industrial**

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo256C-3TN100I	256	1.8V/2.5V/3.3V	78	-3	Lead-Free TQFP	100	IND
LCMxo256C-4TN100I	256	1.8V/2.5V/3.3V	78	-4	Lead-Free TQFP	100	IND
LCMxo256C-3MN100I	256	1.8V/2.5V/3.3V	78	-3	Lead-Free csBGA	100	IND
LCMxo256C-4MN100I	256	1.8V/2.5V/3.3V	78	-4	Lead-Free csBGA	100	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo640C-3TN100I	640	1.8V/2.5V/3.3V	74	-3	Lead-Free TQFP	100	IND
LCMxo640C-4TN100I	640	1.8V/2.5V/3.3V	74	-4	Lead-Free TQFP	100	IND
LCMxo640C-3MN100I	640	1.8V/2.5V/3.3V	74	-3	Lead-Free csBGA	100	IND
LCMxo640C-4MN100I	640	1.8V/2.5V/3.3V	74	-4	Lead-Free csBGA	100	IND
LCMxo640C-3TN144I	640	1.8V/2.5V/3.3V	113	-3	Lead-Free TQFP	144	IND
LCMxo640C-4TN144I	640	1.8V/2.5V/3.3V	113	-4	Lead-Free TQFP	144	IND
LCMxo640C-3MN132I	640	1.8V/2.5V/3.3V	101	-3	Lead-Free csBGA	132	IND
LCMxo640C-4MN132I	640	1.8V/2.5V/3.3V	101	-4	Lead-Free csBGA	132	IND
LCMxo640C-3BN256I	640	1.8V/2.5V/3.3V	159	-3	Lead-Free caBGA	256	IND
LCMxo640C-4BN256I	640	1.8V/2.5V/3.3V	159	-4	Lead-Free caBGA	256	IND
LCMxo640C-3FTN256I	640	1.8V/2.5V/3.3V	159	-3	Lead-Free ftBGA	256	IND
LCMxo640C-4FTN256I	640	1.8V/2.5V/3.3V	159	-4	Lead-Free ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo1200C-3TN100I	1200	1.8V/2.5V/3.3V	73	-3	Lead-Free TQFP	100	IND
LCMxo1200C-4TN100I	1200	1.8V/2.5V/3.3V	73	-4	Lead-Free TQFP	100	IND
LCMxo1200C-3TN144I	1200	1.8V/2.5V/3.3V	113	-3	Lead-Free TQFP	144	IND
LCMxo1200C-4TN144I	1200	1.8V/2.5V/3.3V	113	-4	Lead-Free TQFP	144	IND
LCMxo1200C-3MN132I	1200	1.8V/2.5V/3.3V	101	-3	Lead-Free csBGA	132	IND
LCMxo1200C-4MN132I	1200	1.8V/2.5V/3.3V	101	-4	Lead-Free csBGA	132	IND
LCMxo1200C-3BN256I	1200	1.8V/2.5V/3.3V	211	-3	Lead-Free caBGA	256	IND
LCMxo1200C-4BN256I	1200	1.8V/2.5V/3.3V	211	-4	Lead-Free caBGA	256	IND
LCMxo1200C-3FTN256I	1200	1.8V/2.5V/3.3V	211	-3	Lead-Free ftBGA	256	IND
LCMxo1200C-4FTN256I	1200	1.8V/2.5V/3.3V	211	-4	Lead-Free ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo2280C-3TN100I	2280	1.8V/2.5V/3.3V	73	-3	Lead-Free TQFP	100	IND
LCMxo2280C-4TN100I	2280	1.8V/2.5V/3.3V	73	-4	Lead-Free TQFP	100	IND
LCMxo2280C-3TN144I	2280	1.8V/2.5V/3.3V	113	-3	Lead-Free TQFP	144	IND
LCMxo2280C-4TN144I	2280	1.8V/2.5V/3.3V	113	-4	Lead-Free TQFP	144	IND
LCMxo2280C-3MN132I	2280	1.8V/2.5V/3.3V	101	-3	Lead-Free csBGA	132	IND
LCMxo2280C-4MN132I	2280	1.8V/2.5V/3.3V	101	-4	Lead-Free csBGA	132	IND
LCMxo2280C-3BN256I	2280	1.8V/2.5V/3.3V	211	-3	Lead-Free caBGA	256	IND
LCMxo2280C-4BN256I	2280	1.8V/2.5V/3.3V	211	-4	Lead-Free caBGA	256	IND
LCMxo2280C-3FTN256I	2280	1.8V/2.5V/3.3V	211	-3	Lead-Free ftBGA	256	IND
LCMxo2280C-4FTN256I	2280	1.8V/2.5V/3.3V	211	-4	Lead-Free ftBGA	256	IND
LCMxo2280C-3FTN324I	2280	1.8V/2.5V/3.3V	271	-3	Lead-Free ftBGA	324	IND
LCMxo2280C-4FTN324I	2280	1.8V/2.5V/3.3V	271	-4	Lead-Free ftBGA	324	IND

Date	Version	Section	Change Summary
April 2006 (cont.)	02.0 (cont.)	Architecture (cont.)	<p>"Top View of the MachXO1200 Device" figure updated.</p> <p>"Top View of the MachXO640 Device" figure updated.</p> <p>"Top View of the MachXO256 Device" figure updated.</p> <p>"Slice Diagram" figure updated.</p> <p>Slice Signal Descriptions table updated.</p> <p>Routing section updated.</p> <p>sysCLOCK Phase Locked Loops (PLLs) section updated.</p> <p>PLL Diagram updated.</p> <p>PLL Signal Descriptions table updated.</p> <p>sysMEM Memory section has been updated.</p> <p>PIO Groups section has been updated.</p> <p>PIO section has been updated.</p> <p>MachXO PIO Block Diagram updated.</p> <p>Supported Input Standards table updated.</p> <p>MachXO Configuration and Programming diagram updated.</p>
		DC and Switching Characteristics	<p>Recommended Operating Conditions table - footnotes updated.</p> <p>MachXO256 and MachXO640 Hot Socketing Specifications - footnotes updated.</p> <p>Added MachXO1200 and MachXO2280 Hot Socketing Specifications table.</p> <p>DC Electrical Characteristics, footnotes have been updated.</p> <p>Supply Current (Sleep Mode) table has been updated, removed "4W" references. Footnotes have been updated.</p> <p>Supply Current (Standby) table and associated footnotes updated.</p> <p>Initialization Supply Current table and footnotes updated.</p> <p>Programming and Erase Flash Supply Current table and associated footnotes have been updated.</p> <p>Register-to-Register Performance table updated (rev. A 0.19).</p> <p>MachXO External Switching Characteristics updated (rev. A 0.19).</p> <p>MachXO Internal Timing Parameters updated (rev. A 0.19).</p> <p>MachXO Family Timing Adders updated (rev. A 0.19).</p> <p>sysCLOCK Timing updated (rev. A 0.19).</p> <p>MachXO "C" Sleep Mode Timing updated (A 0.19).</p> <p>JTAG Port Timing Specification updated (rev. A 0.19).</p> <p>Test Fixture Required Components table updated.</p>
		Pinout Information	<p>Signal Descriptions have been updated.</p> <p>Pin Information Summary has been updated. Footnote has been added.</p> <p>Power Supply and NC Connection table has been updated.</p> <p>Logic Signal Connections have been updated (PCLKTx_x --&gt; PCLKx_x)</p>
		Ordering Information	<p>Removed "4W" references.</p> <p>Added 256-ftBGA Ordering Part Numbers for MachXO640.</p>
May 2006	02.1	Pinout Information	<p>Removed [LOC][0]_PLL_RST from Signal Description table.</p> <p>PCLK footnote has been added to all appropriate pins.</p>
August 2006	02.2	Multiple	Removed 256 fpBGA information for MachXO640.